

PHT

Link To The World

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12"compatible Single Wafer Processing
Quartz Glass Wafer Transfer Device



12" compatible Single Wafer Processing

Equipment Standard

Overview

This system automatically transfers $\phi 300$ mm (12") quartz glass wafers between carriers on stages (1) and (2) in a single-wafer operation.

Processed Materials

1. Wafer

- $\phi 300$ mm Quartz glass · Notch
- Diameter $\phi 300$ mm ± 0.2 mm
- Thickness 400 ~ 700 μ m
- Warpage 40 μ m or less
- Contactable Range Backside of wafer

Throughput

- For notch matching
- Tact time and transfer time: 6 min 30 sec / 25 sheets or less

External Dimension

Please see attached drawing.

2. Carrier

- Auto Door FOSB Type Designation
- FOUP Type Designation
- Wafer storage pitch 10mm

Part Specs

Part Specs (1)

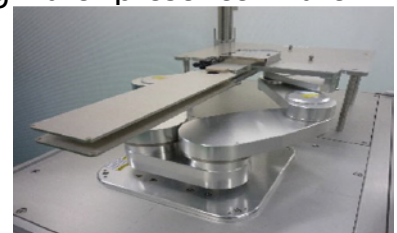
Stage 1 (loader)

1. Stage at front left of device
2. Compatible carriers
 - ① AutoDoor FOSB Wafer storage pitch 10mm \times 25wafers
 - ② FOUP SEMI standard product Wafer storage pitch 10mm \times 25wafers
3. Sensor Functions
 - ① Install a transmission mapping sensor for checking wafer presence in the cassette.

Part Specs (2)

Stage 2 (loader)

1. Stage at front right of device
2. Compatible carriers
 - ① AutoDoor FOSB Wafer storage pitch 10mm \times 25wafers
 - ② FOUP SEMI standard product Wafer storage pitch 10mm \times 25wafers
3. Sensor Functions
 - ① Install a transmission mapping sensor for checking wafer presence in the cassette.



Part Specs (3)

1. Operation Telescopic · Swivelling · up/down 3-axis robot (servo motor driven)
2. Robot hand Made of CFRP Wafer contact area PEEK Edge-holding system
3. Wafer transfer specifications The basic procedure is: lower cassette - take-out → upper cassette - storage.
4. Parallel transfer and extraction shall also be possible.